

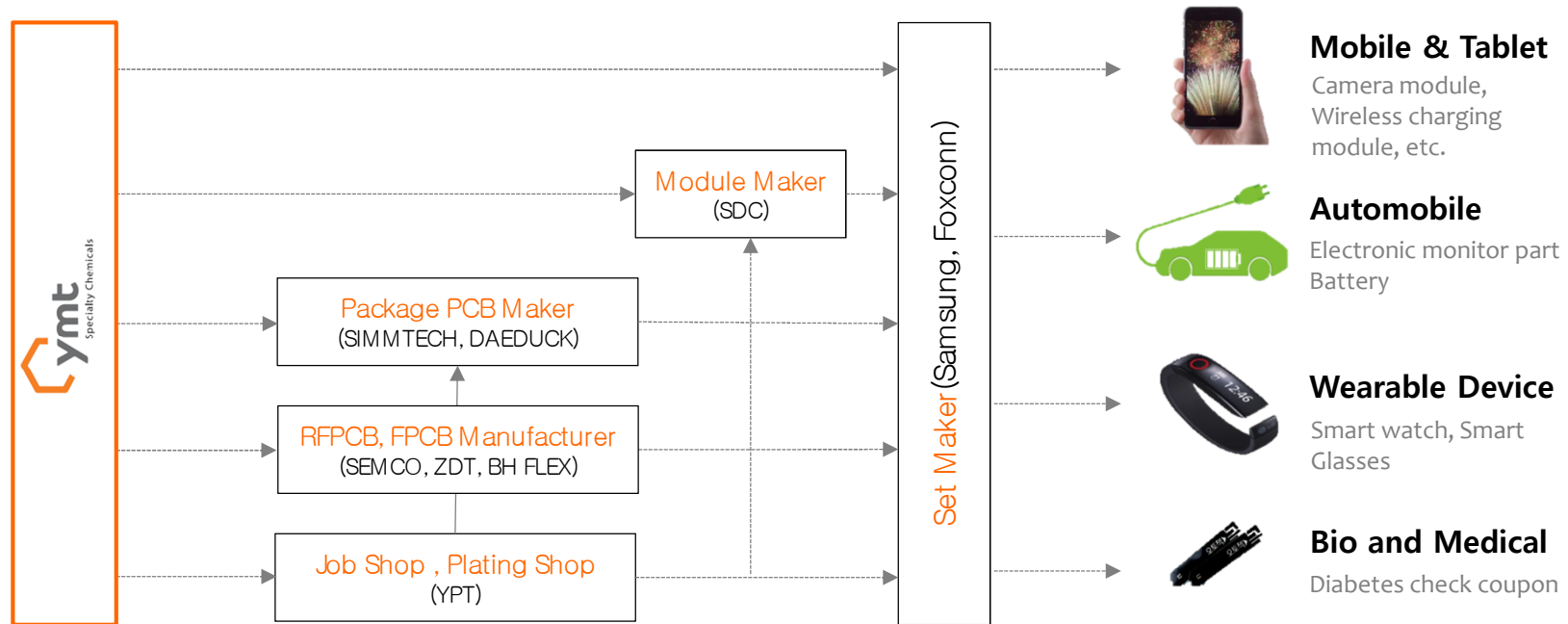
INVESTOR RELATIONS

2019 YMT IR BOOK
Your Most trustworthy



Company Introduction

YMT is a global company that directly researches, produces, and supplies high value-added plating chemicals for high-end PCB manufacturing processes.



YMT is chemical & electronic materials supplier for F/RF-PCB manufacturers located in Korea, China, and Vietnam. Based on plating, technology in PCB field, YMT is expanding the market to PKG PCB and electronic materials.

Company Introduction

GLOBAL NETWORK

YMT HQ

- Incheon, Korea
- 139 employees (HQ), / 250 employees (Total)
- 2 R&D Centers
- Main Manufacturing location

YMT China (Shenzhen) Co., Ltd

No.509, Hongan Business Center, Xiqiao Integration BLDG, Beihuan RD, Shajing St, Baoan District, Shenzhen, CN518125
Tel +86-755-2946-6201

YMT China (Shenzhen) Kunshan Branch

Lujia Town, Kunshan City, Jiangsu Province Hefeng Villang, Jinzhu Road No.18 CN215331
Tel +86-0512-3669-8439

YMT Taiwan Branch

1F, No.51, Housheng RD, Luzhu City, Taoyuan County 338, Taiwan
Tel +886-3-3220808

Rizhao Factory

South of Shanghai RD, West of Xian Dai RD, Rizhao Economic Development Zone Rizhao City, Shandong Province, China 276800
Tel +86-633-227-8778

YMT Vina(Vietnam) Co., Ltd

F6, Room602, MB Bac Ninh Building, No.24, Ly Thai To Street, Bac Ninh City, Vietnam
Tel. +84-24-1625-1238 Fax. +84-24-1625-1288

YMT Europe Office

Drahobejova 1019/27, Praha 9 - Libeň (Zip : 19000)

본사/1공장 HQ/Factory 1

인천광역시 남동구 남동대로 153번길 30
Tel. 032-821-8277 Fax. 032-821-8271

2공장 Factory 2

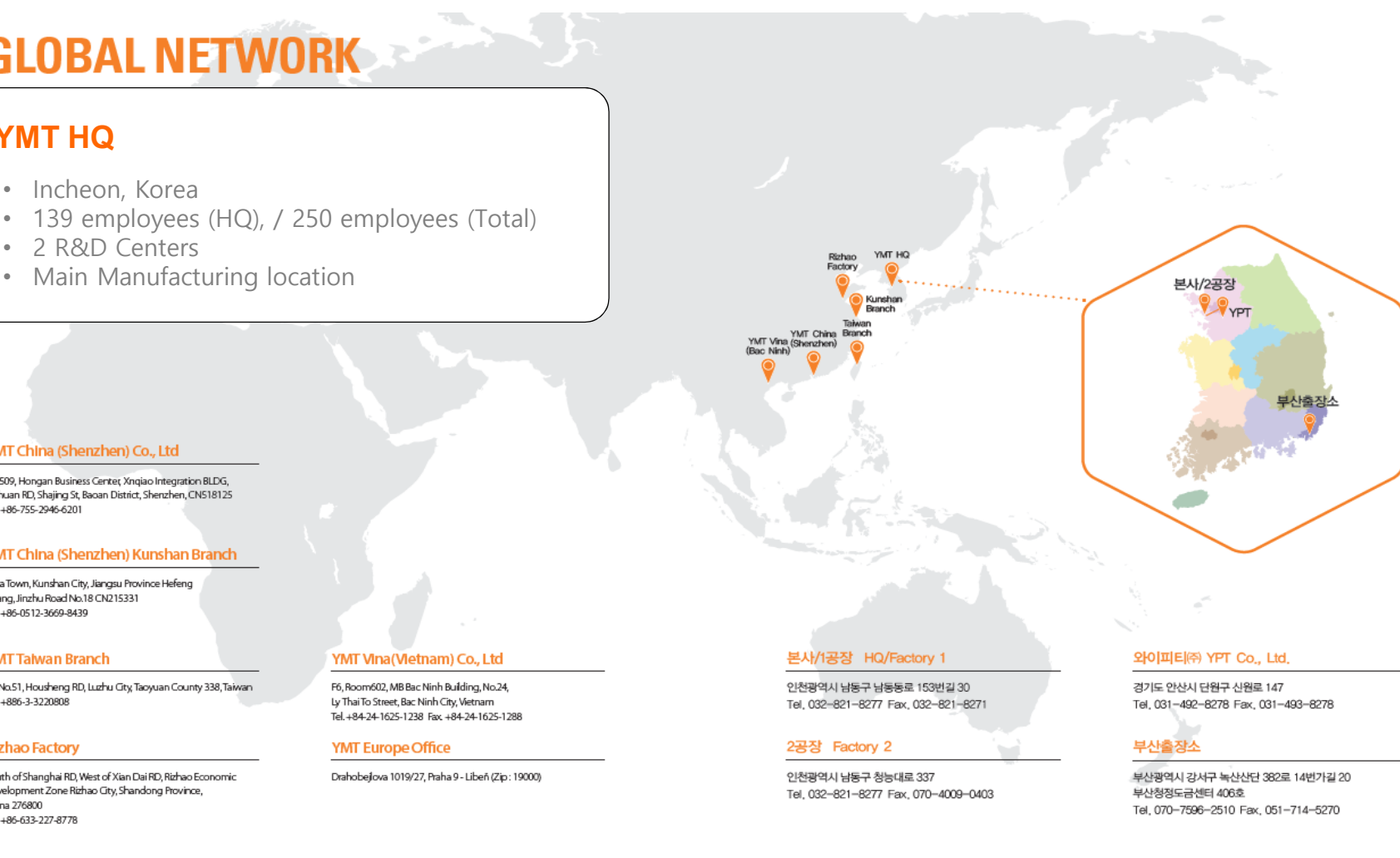
인천광역시 남동구 청능대로 337
Tel. 032-821-8277 Fax. 070-4009-0403

와이피티(주) YPT Co., Ltd.

경기도 안산시 단원구 신원로 147
Tel. 031-492-8278 Fax. 031-493-8278

부산출장소

부산광역시 강서구 녹산산단 382로 14번가길 20
부산청정도금센터 406호
Tel. 070-7596-2510 Fax. 051-714-5270



Customer List

PCB Maker Direct Customer	    
	    
	    
Set Maker	     
Semi-conductor Maker	   
Display Maker	  

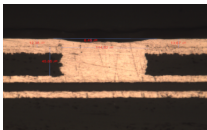
Products Introduction

Chemical Business



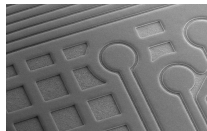
Finish Plating Chemical

- Plating PCB surfaces by using precious metals such as gold and palladium.
 - ✓ 1st in global market share in gold plating for F/RF-PCB
 - ✓ Adopted by Apple, Samsung



Copper Plating Chemical

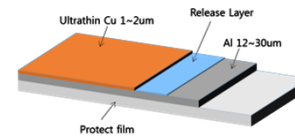
- Process for forming an electrical connection between layers of Multi layer substrate
 - ✓ Electroless Copper plating
 - ✓ Electronic Copper plating



Process Chemical

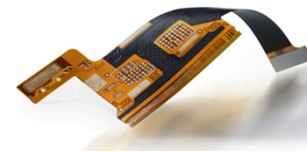
- Etching, developing and other chemical to form circuitry of substrate
 - ✓ Etching, developing and other chemical for PCB
 - ✓ Process Chemical for MSAP
 - ✓ Flux Cleaner

Others



Electronic Materials

- Materials
 - ✓ Ultra-thin copper Foil
 - ✓ EMI Shield
- Roll to Roll
 - ✓ RTR copper plating outsourcing



Plating Outsourcing [YPT]

- Gold plating outsourcing
 - ✓ FPCB, RFPCB
 - ✓ PCB for Camera module
- Via-fill copper plating outsourcing



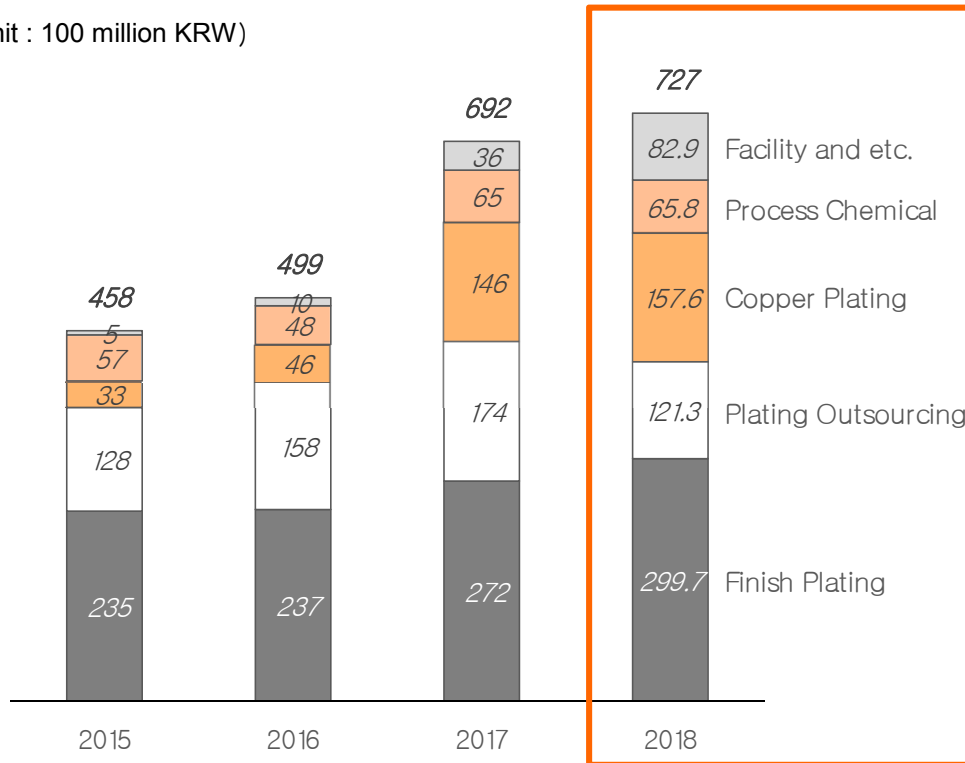
Facility [Beyond Solution]

- Gold and copper plating facility sales, installation and maintenance services
 - ✓ Selling bundled with YMT chemical
 - ✓ Via-fill facility improvement, customer relocation to Vietnam, etc.

Sales Result

- Finish Plating
- Plating Outsourcing
- Copper Plating
- Process Chemical
- Facility and etc.

(Unit : 100 million KRW)



- **Earning record revenue of 72.7 billion won in 2018**
 - ✓ 5% (3.5 billion KRW) increase over 2017.
- **Steady growth of finish plating chemical**
 - ✓ 2.8 billion KRW increase over last year
 - ✓ Expanding the customer base in China, Vietnam
- **Facility sales growth**
 - ✓ 6 billion KRW in facility sales in 2018
 - ✓ Facility sales by Beyond Solution and YMT
- **Plating outsourcing(YPT) revenue down by 5.3 billion KRW**
 - ✓ Transfer of domestic gold plating production volume to Vietnam.
 - ✓ Delay in mass-production of Via-fill outsourcing

2019 Business Forecast

1) Launching of Foldable Smartphone, 2) Opening of 5G Market.



Increased number of PCBs per unit

- **Increased mounting of display panels**
 - ✓ 2 panels in a Galaxy Fold
 - ✓ This increases PCB for display.
- **Increased PCB for batteries**
 - ✓ Increased battery pack as display area and number of displays increase
- **Increase the number of camera modules**
 - ✓ Total of 6 camera modules
- **Changing antenna specifications from LDS to FPCB**
 - ✓ Switching to thin FPCB due to increasing number of antennas for 5G high frequency

Prospect to benefit major customers
Scale up the PCB overall market

High-Specification of PCB

- **Expanding the SLP market**
 - ✓ Insufficient space due to expansion of modules such as batteries
 - ✓ Essential HDI miniaturization
- **Fine pitch needs increased**
 - ✓ PCB area is reduced, but circuit area in PCB is increased
 - ✓ Increasing high-specific chemical needs
- **Extend high-layer PCB**
 - ✓ Increased needs for high-layer PCBs as PCB areas are reduced
 - ✓ Expanding market needs for high-end, high-layer PCB technologies such as Via-fill

Expectations of chemical ASP's rise
Initial sell to major customers is currently under way

Material change

- **Increased needs for ultra-thin copper foil**
 - ✓ Material essential to PCB's light, thin, short, small trend as like SLP
- **Change of EMI shielding materials**
 - ✓ Mobile shielding materials change for 5G high frequency
- **Material change to prevent loss of signal transmission rate**
 - ✓ Change of materials and processes are required to prevent signal loss, which is most important in 5G.
 - ✓ Released Low-roughness ultra-thin copper foil, Non etching low profile roughness chemicals, etc.

Nanotus(Non etching process) is under development. Testing in ultra-thin copper foil with major customers

2019 Business Forecast

Market Forecast

- Mobile-related PCB production is expected to be similar with last year, but growth in other areas such as automobiles, medical, etc.
- Acceleration for movement of PCB production bases to Vietnam
- Increase sales associated with the release of foldable and 5G

Chemical Business

Finish Plating Chemical

- Prospects for expanding sales of materials related to increasing PCB for OLED
- Growth in sales of materials for camera modules in China due to expansion of dual or triple camera adoption
- Expect growth in the market with the start of mass-production of customers in Vietnam

Copper Plating Chemical

- Growth is expected due to increased market volume and market share within customers
- Expand new sales related to electronic copper plating (Via-Fill)

Process Chemical

- Prospects to increase sales and acquire new customers related to SLP and PKG PCBs
- Entering the new process market for 5G, as like Nanotus, low-roughness etching process, etc.

Others

Plating Outsourcing

- Completion of Vietnam plant is scheduled in April, gold plating outsourcing will be mass-produced in 2nd half of this year
- YPT expects to start Via-fill mass-production in this year and sales will be increased than last year

Electronic Materials

- Sales related to domestic Signage (OLED panel) manufacturers
- EMI shielding materials are currently being promoted to customers
- Copper foil import/processing business is deciding on approval for mass-production by customers and is expected to be supplied within first half of this year.

Facility and etc.

- Increase in facility sales due to transfer of customers to foreign countries and increase sales of high-quality PCB plating facilities
- Launch of facility business in China market

Income Statement

(Unit : 100 million won)

	2018	%	2017	%
I. Sales	727.4	100%	691.9	100%
II. Cost of sales	447.9	61.6%	415.3	60.0%
III. Gross profit	279.5	38.4%	276.6	40.0%
Sales and administrative expenses	135.6	18.6%	115.5	16.7%
IV. Operating income	143.9	19.8%	160.8	23.2%
Other gains	8.9	1.2%	14.2	2.1%
Other losses	23.9	3.2%	12.7	1.8%
Finance income	13.5	1.9%	3.2	0.5%
Finance costs	23.5	3.2%	44.8	6.5%
Losses on equity method	0.3	0.0%	-	-
V. Profit before tax	118.6	16.3%	120.6	17.4%
Income tax expense	20.7	2.9%	30.4	4.4%
VI. Profit	97.9	13.5%	90.1	13.0%

Profitability Indicator

	2018	2017
Operating profit ratio	19.8%	23.2%
Capital net profit rate	13.5%	13.0%
EBITDA (percent margin)	163.4 (22.46%)	155.0 (22.40%)
ROE	12.01%	14.20%
Asset turnover ratio	57.24%	60.71%

Balance Sheet

(Unit : 100 million won)

	2018	2017
Assets		
Cashable assets	276.1	224.2
Trade receivable	206.6	228.1
Tangible assets	560.5	465.3
Other assets	227.6	222.1
Total assets	1,270.8	1,139.7
Liabilities		
Trade payables	37.8	37.6
Borrowings	329.9	346.7
Convertible bond	68.9	-
Other liabilities	90.1	90.4
Total liabilities	526.7	474.7
Equity		
Issued capital	37.0	18.5
Capital surplus	219.5	232.7
Retained earnings	403.4	334.6
Other equity	84.2	79.2
Total equity	744.1	665.0
Total equity and liabilities	1,270.8	1,139.7

Cash Flow

(Unit : 100 million won)

	2018	2017
Cash at beginning of period	224.2	108.5
Cash flows from operating activities	176.0	81.6
Profit	97.9	90.1
Depreciation cost	37.5	27.2
Cash flows from investing activities	(160.7)	(167.9)
Purchase of tangible asset	(120.3)	(167.7)
Cash flows from financing activities	33.6	210.6
Proceeds (repayments) of borrowings	(16.8)	93.1
Acquisition (disposition) of treasury shares	(19.6)	13.2
Issuance of CB	70	-
Issuance of new stocks	-	104
Net increase in cash	48.9	124.3
Effect of exchange rate changes	3.0	(8.5)
Cash at end of period	276.1	224.2

END OF DOCUMENT

Thank you.